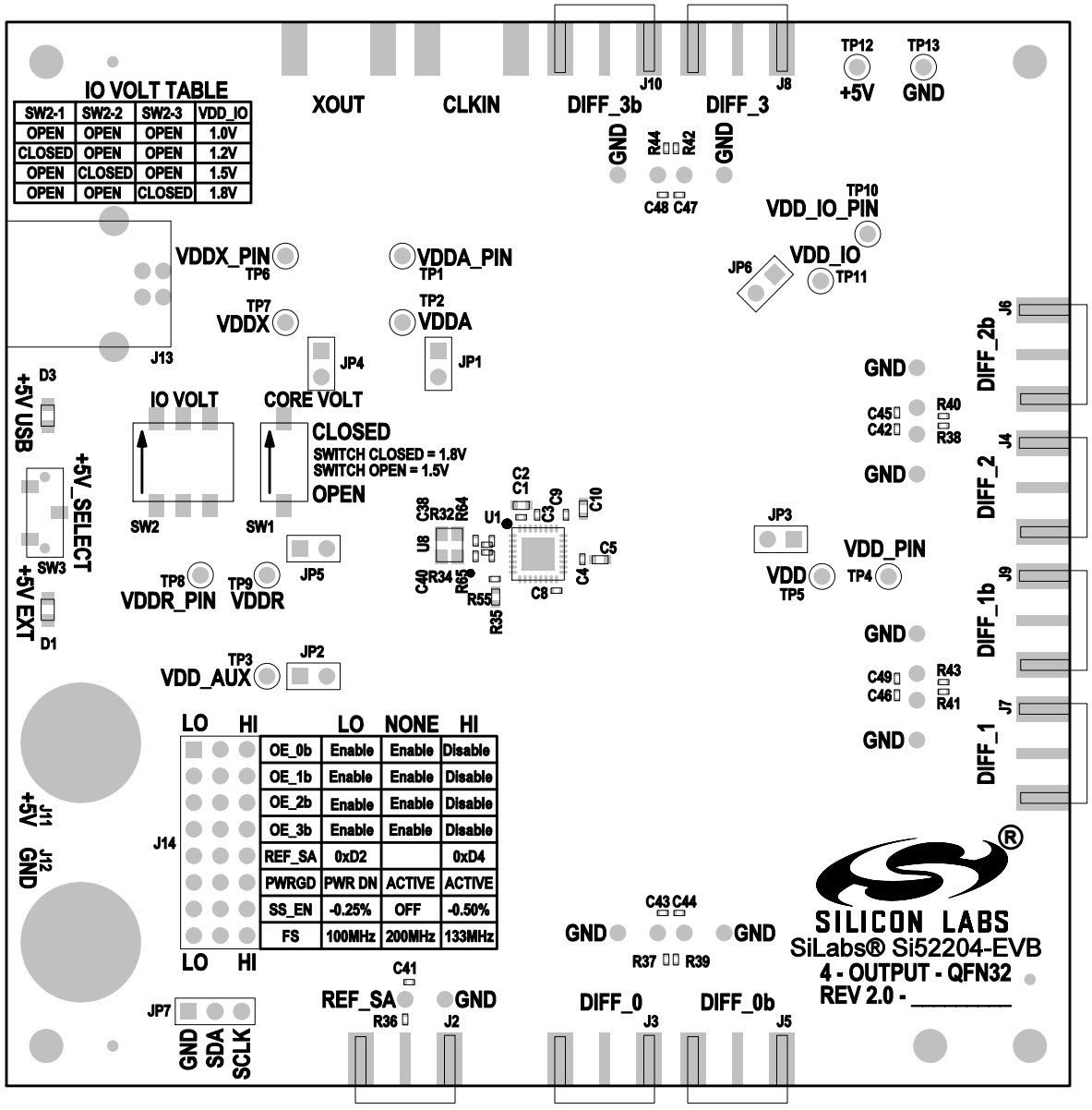
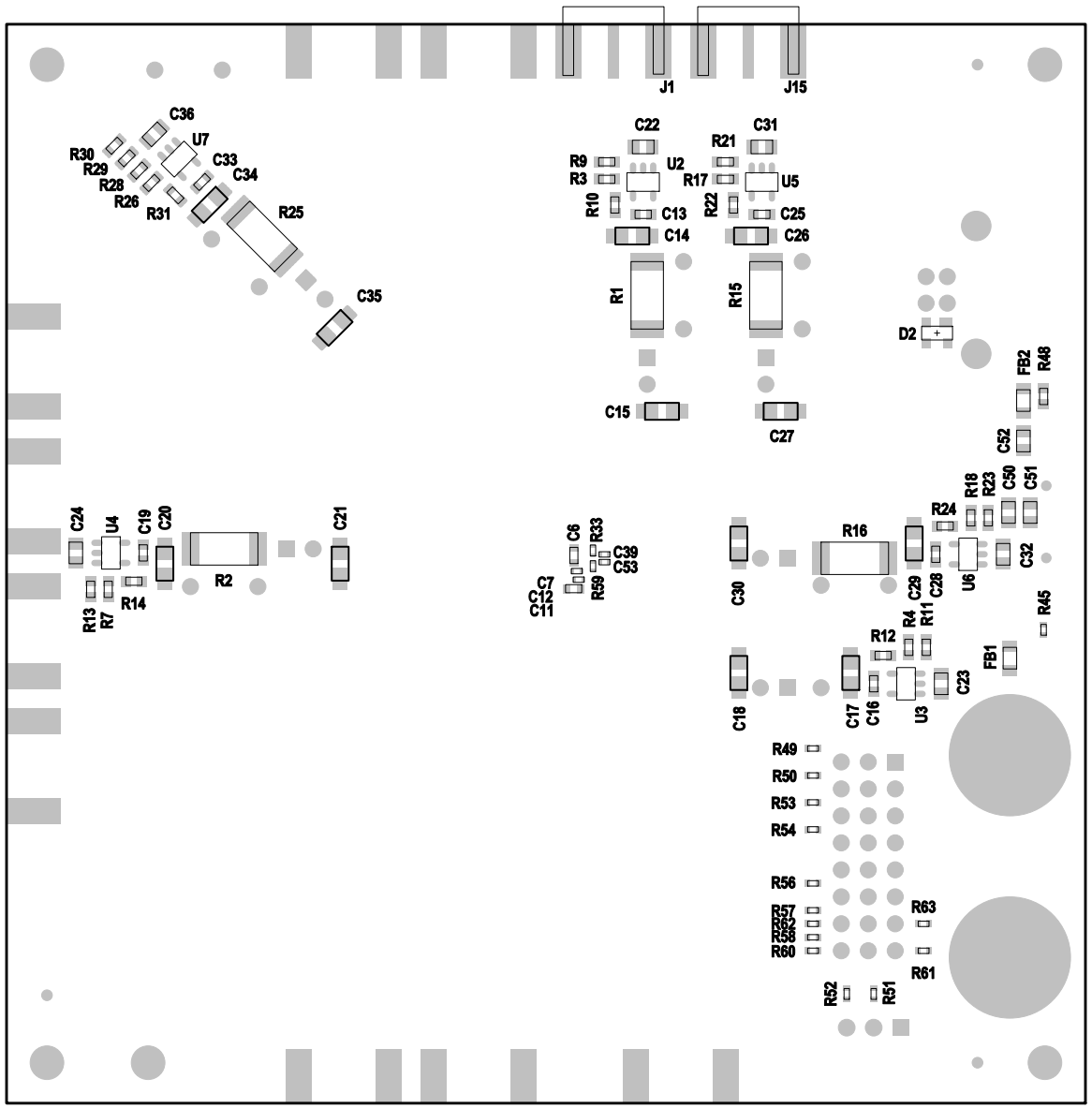
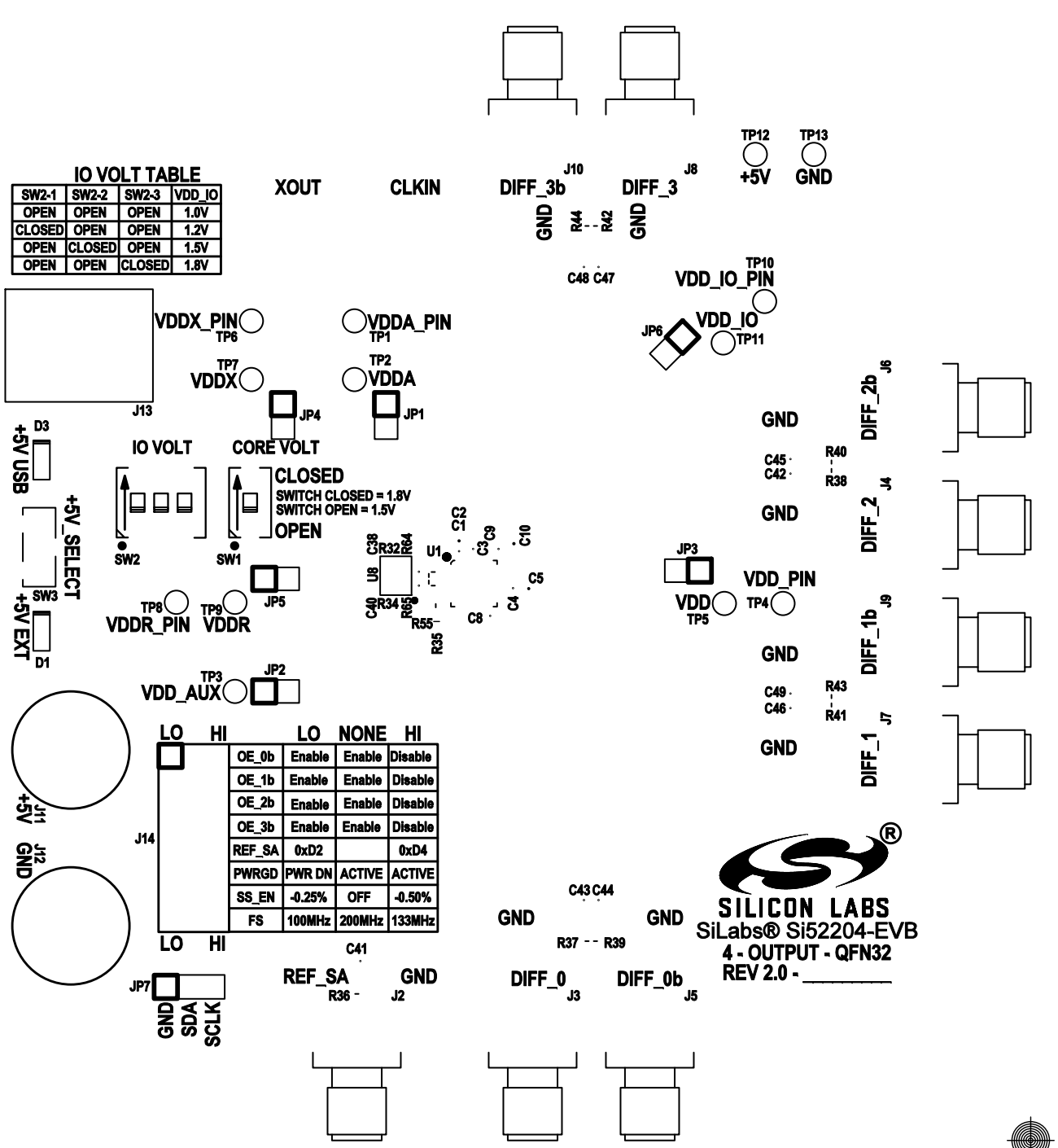


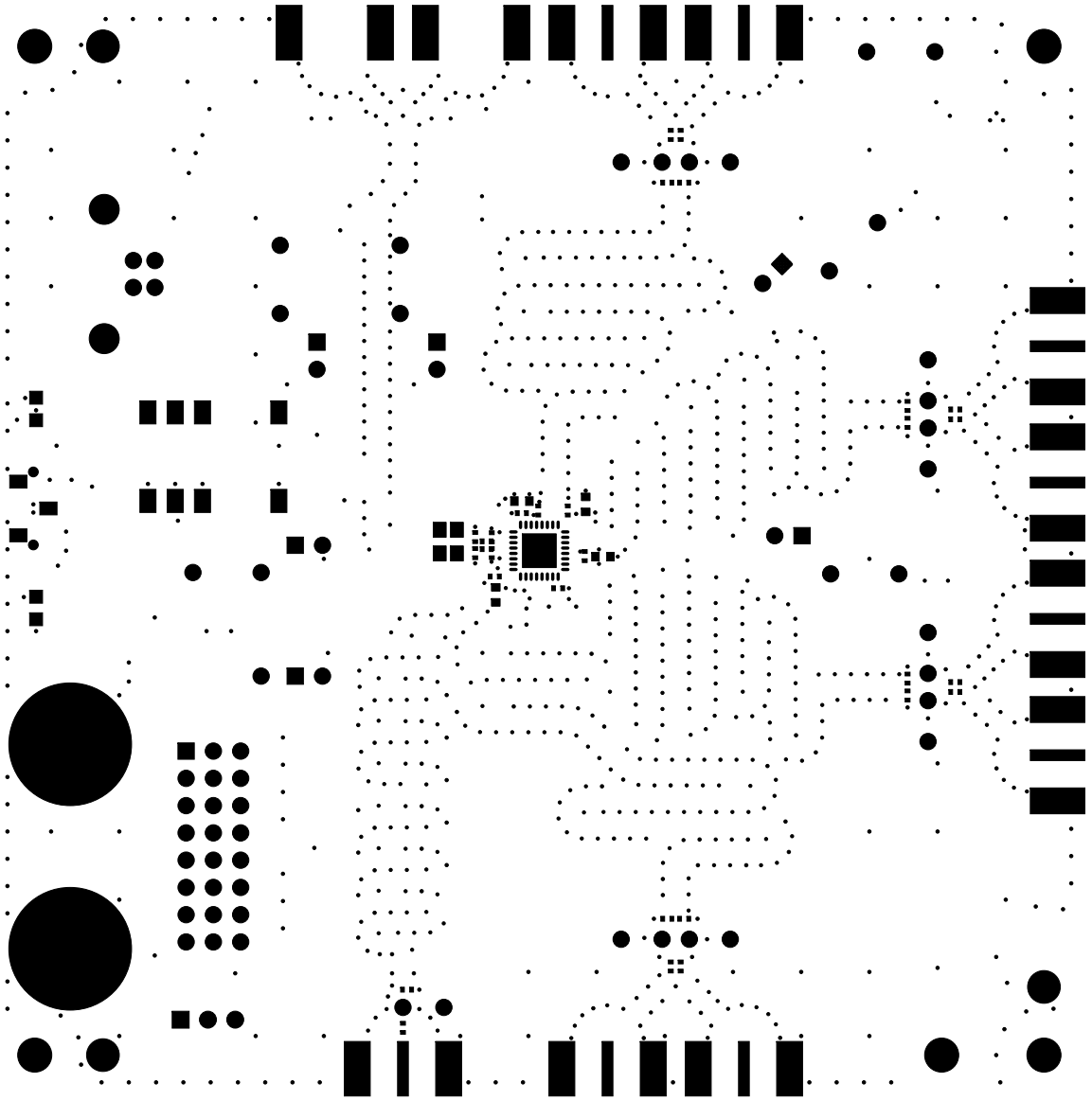
PRIMARY SIDE
PRIMARY SILKSCREEN



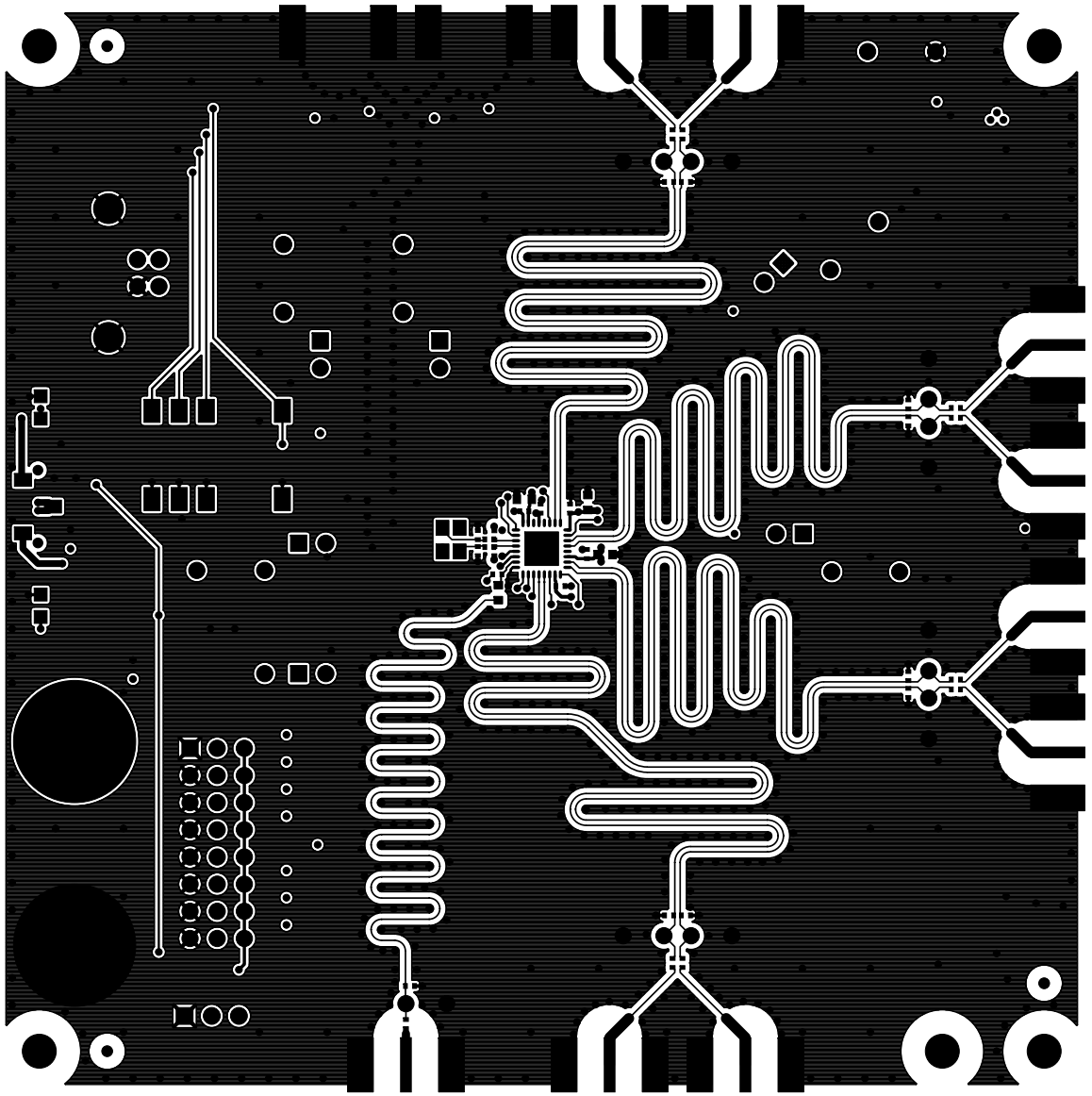
SECONDARY SILKSCREEN
SECONDARY SIDE



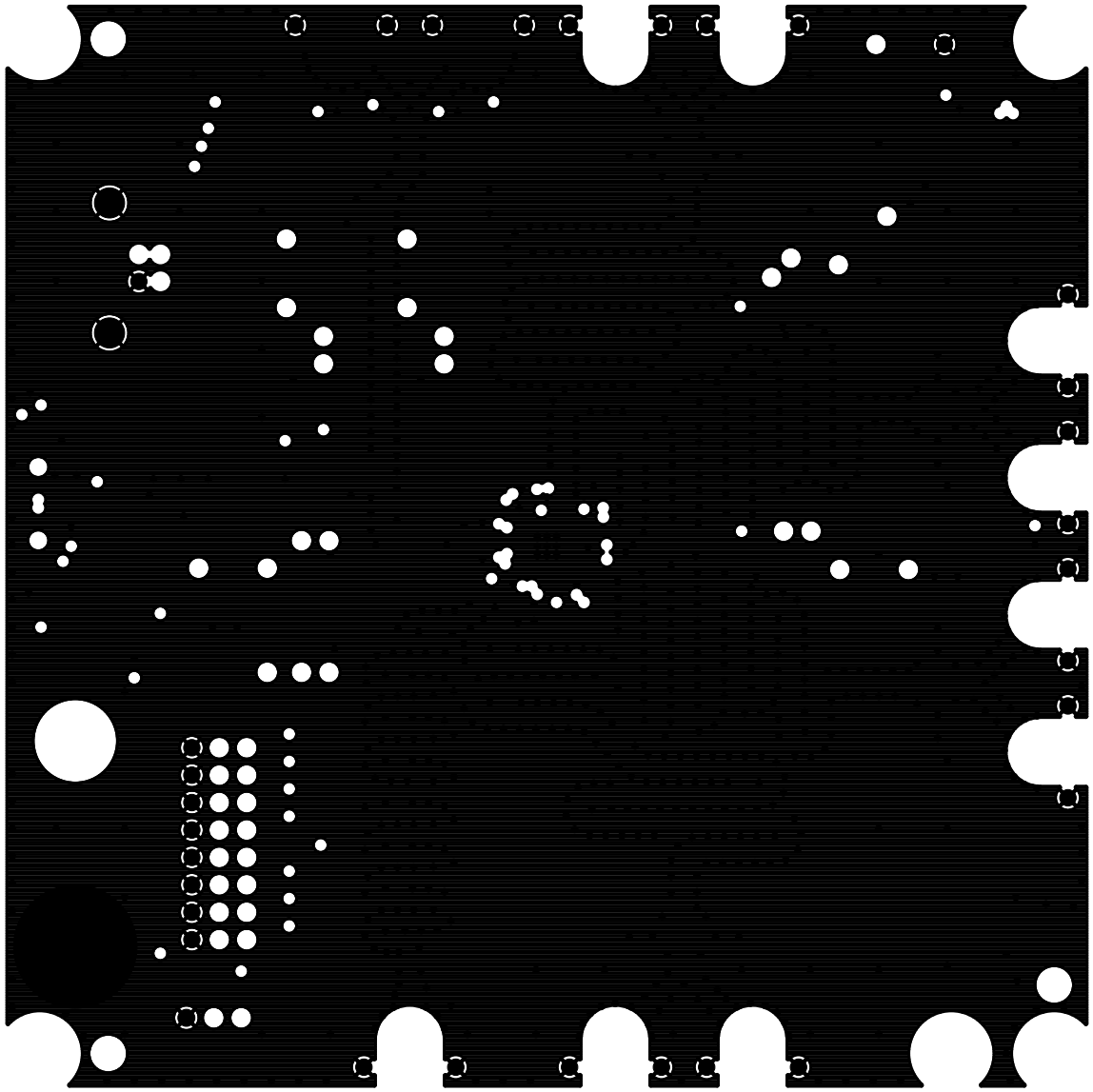
PRIMARY SILKSCREEN



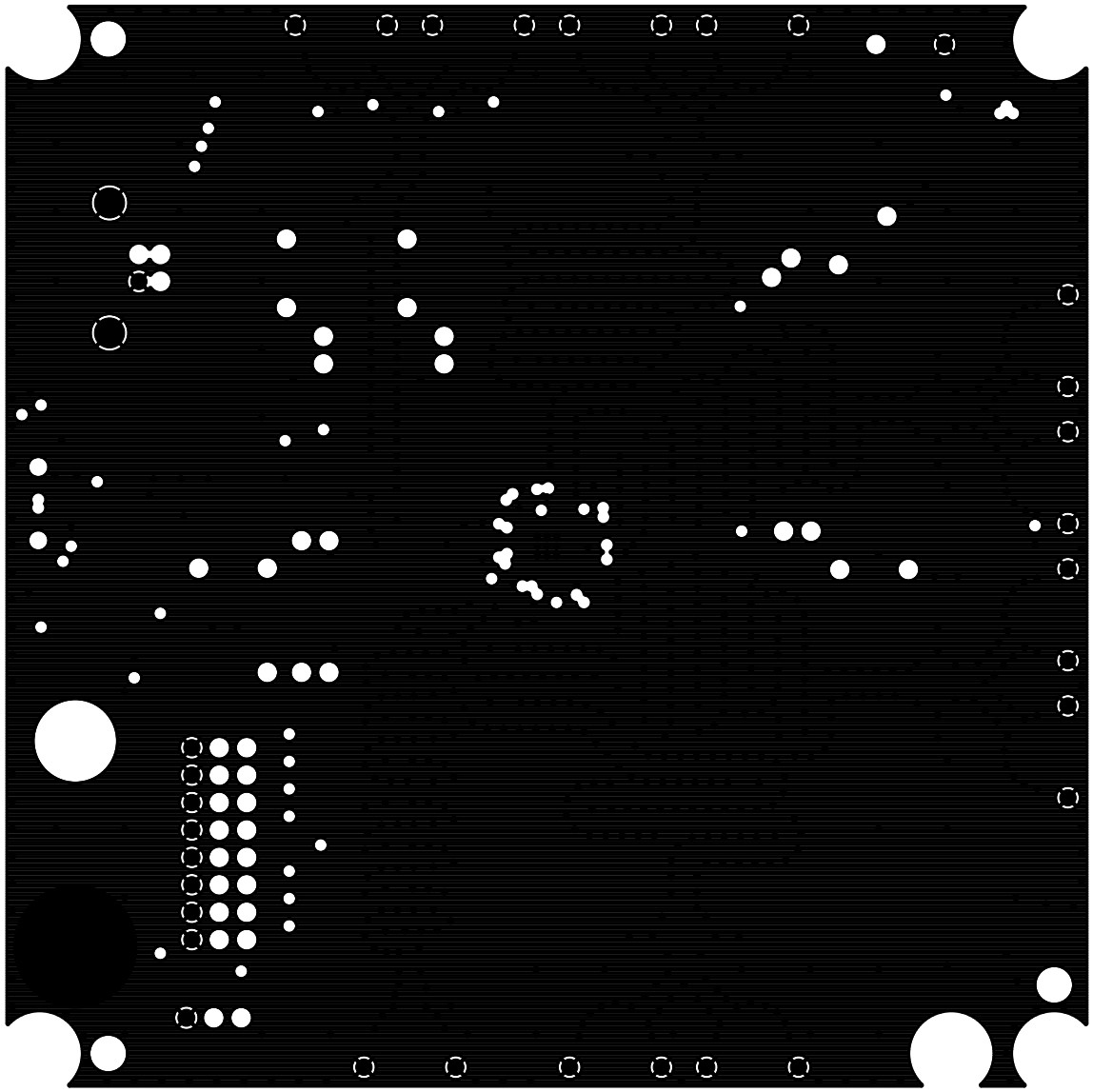
PRIMARY SOLDER MASK



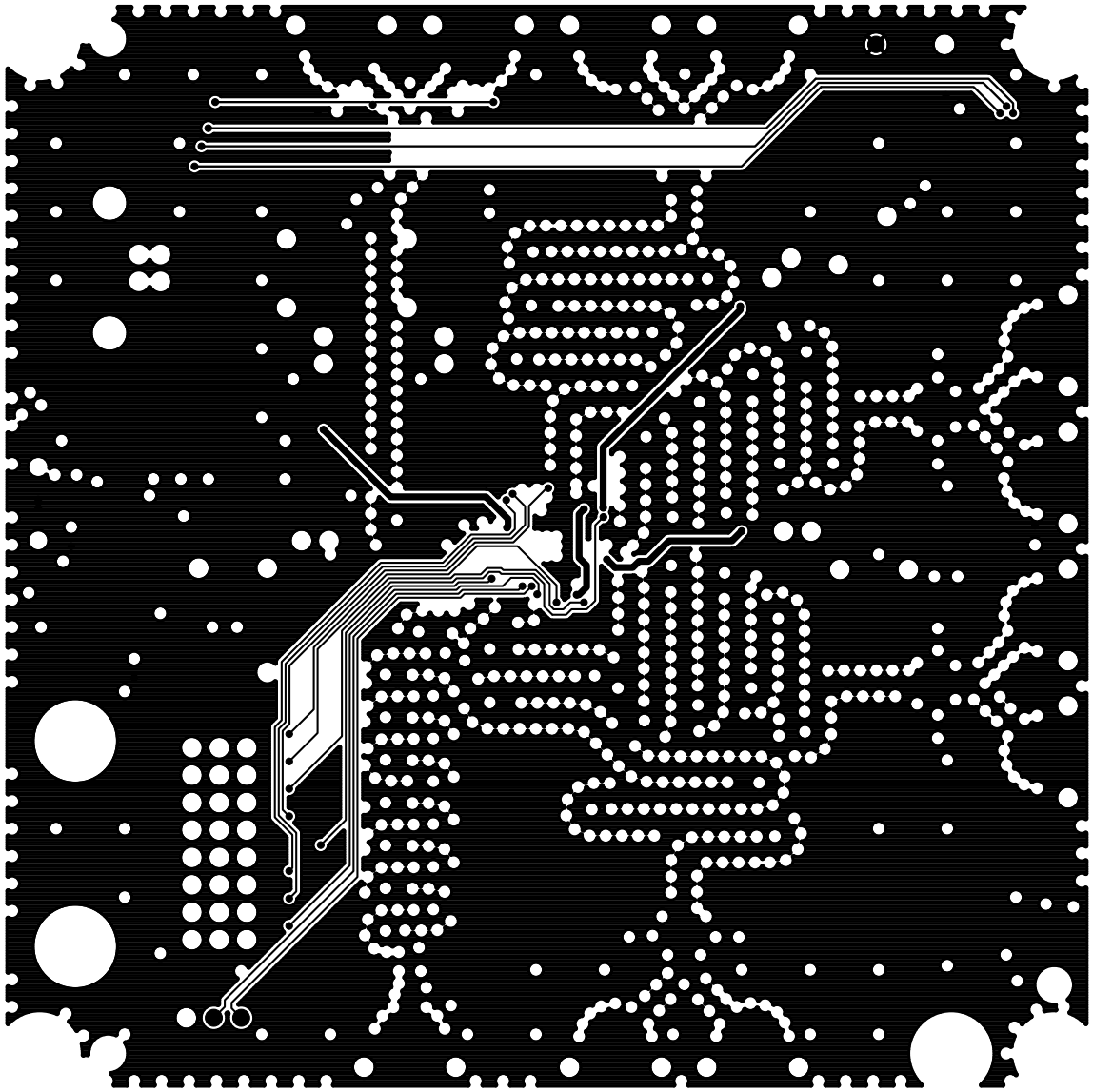
PRIMARY SIDE



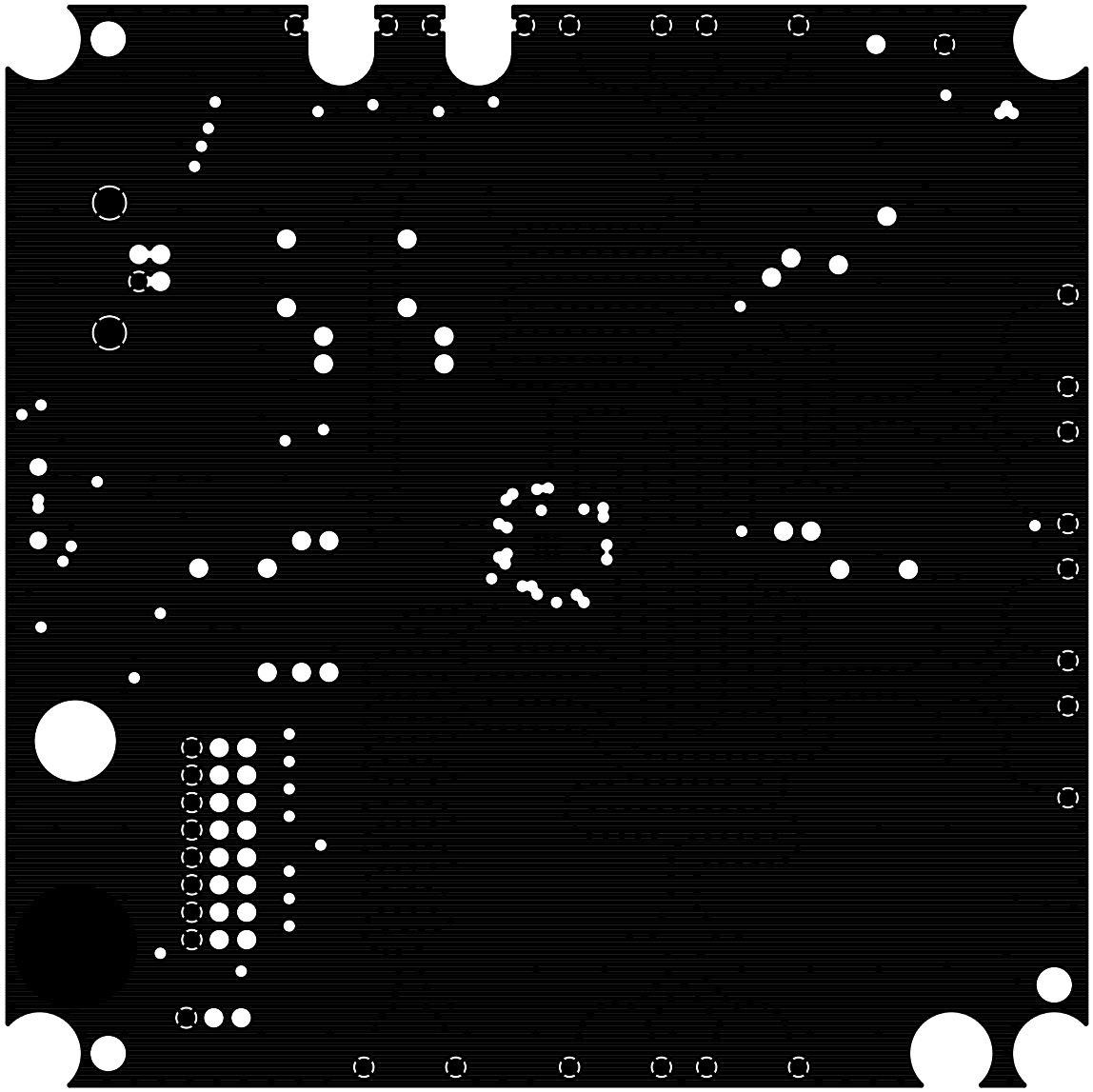
L02 (GROUND PLANE)



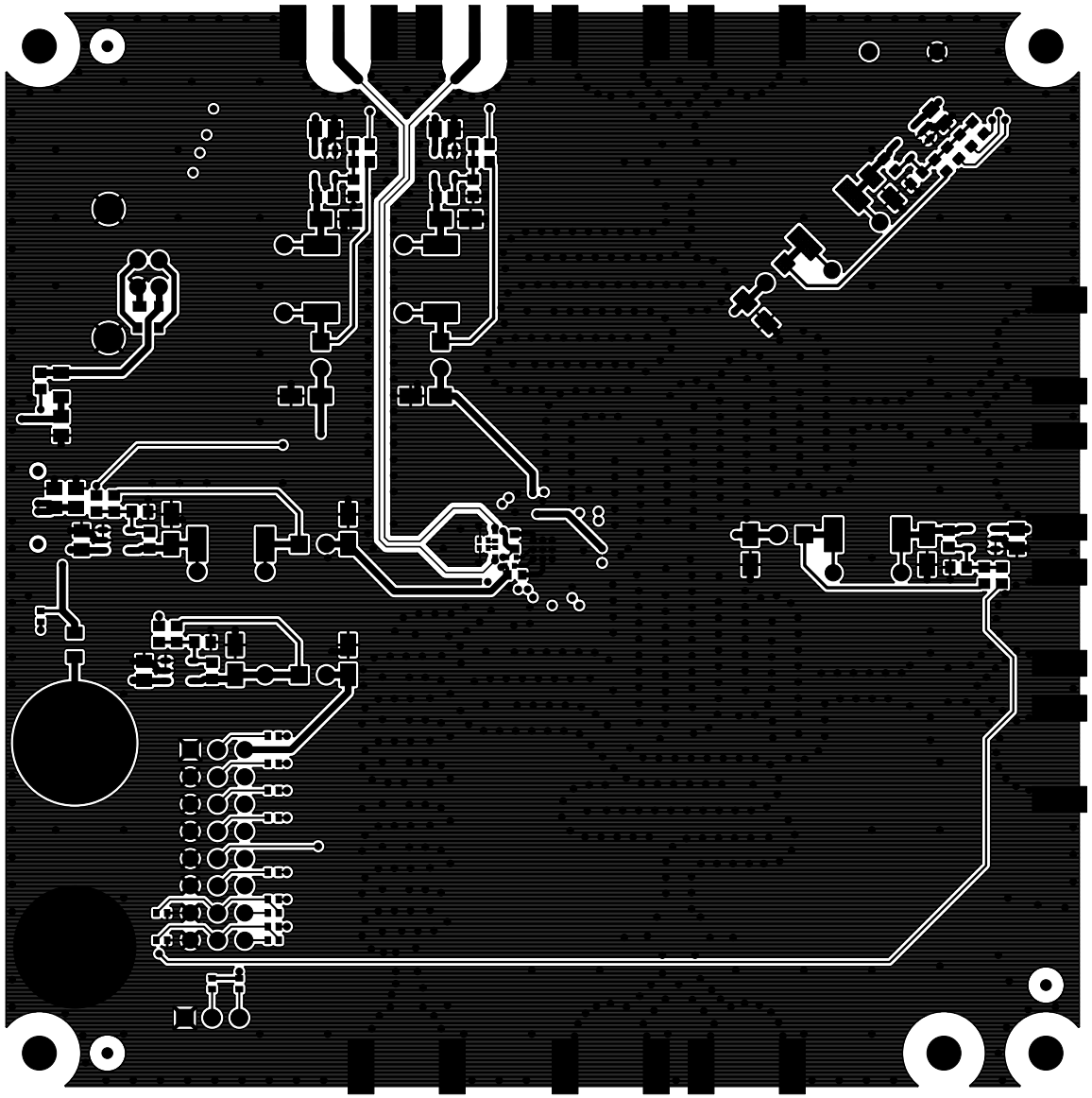
L03 (GROUND PLANE)



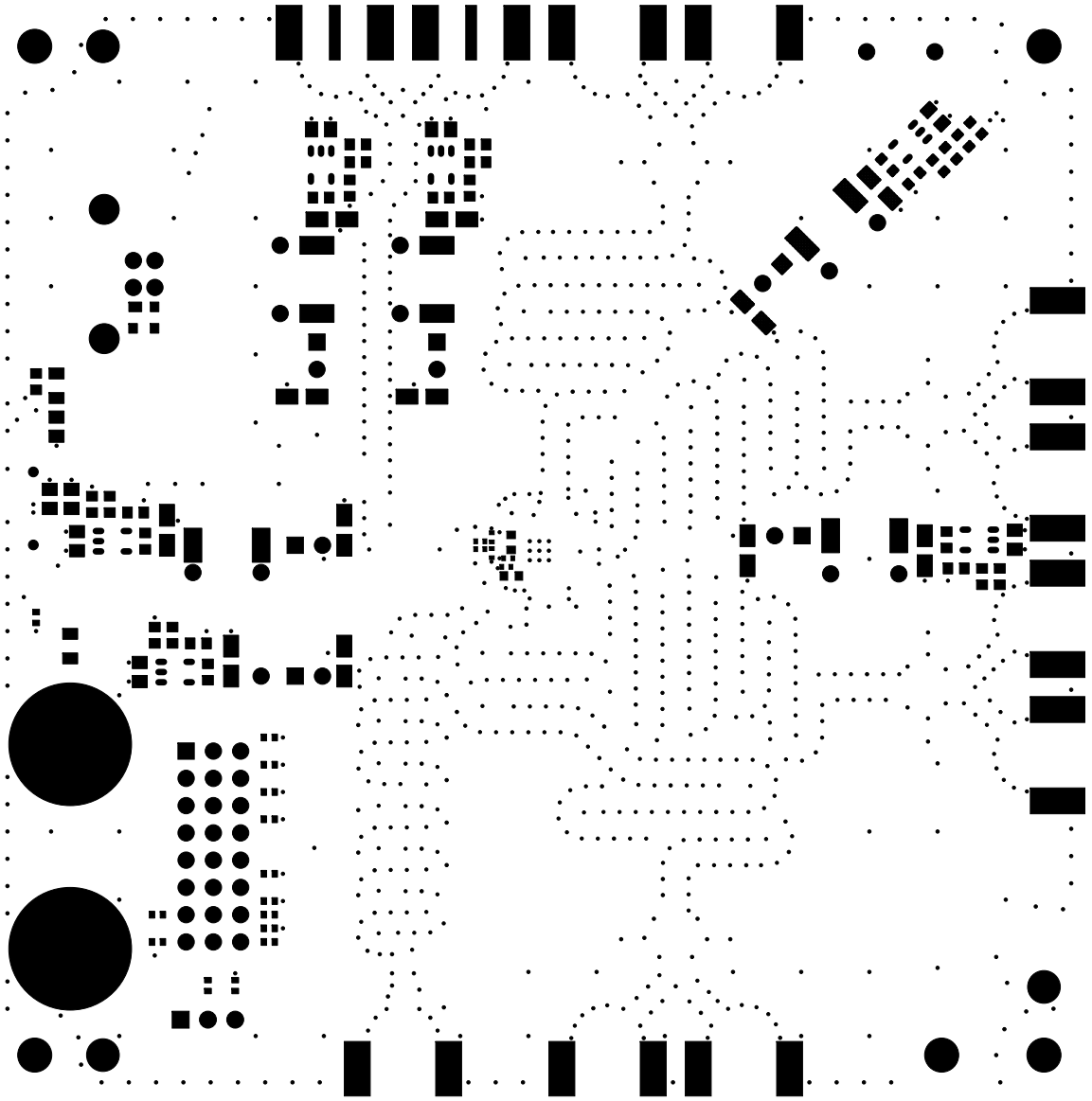
L04 (+5V/ROUTE)



L05 (GROUND PLANE)

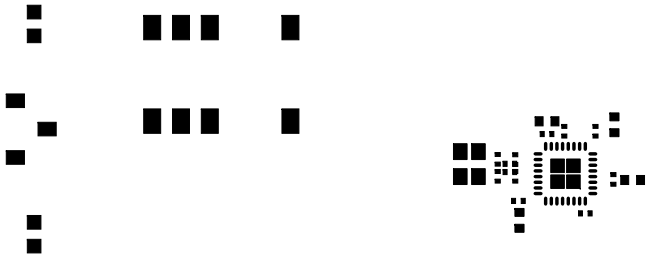


SECONDARY SIDE

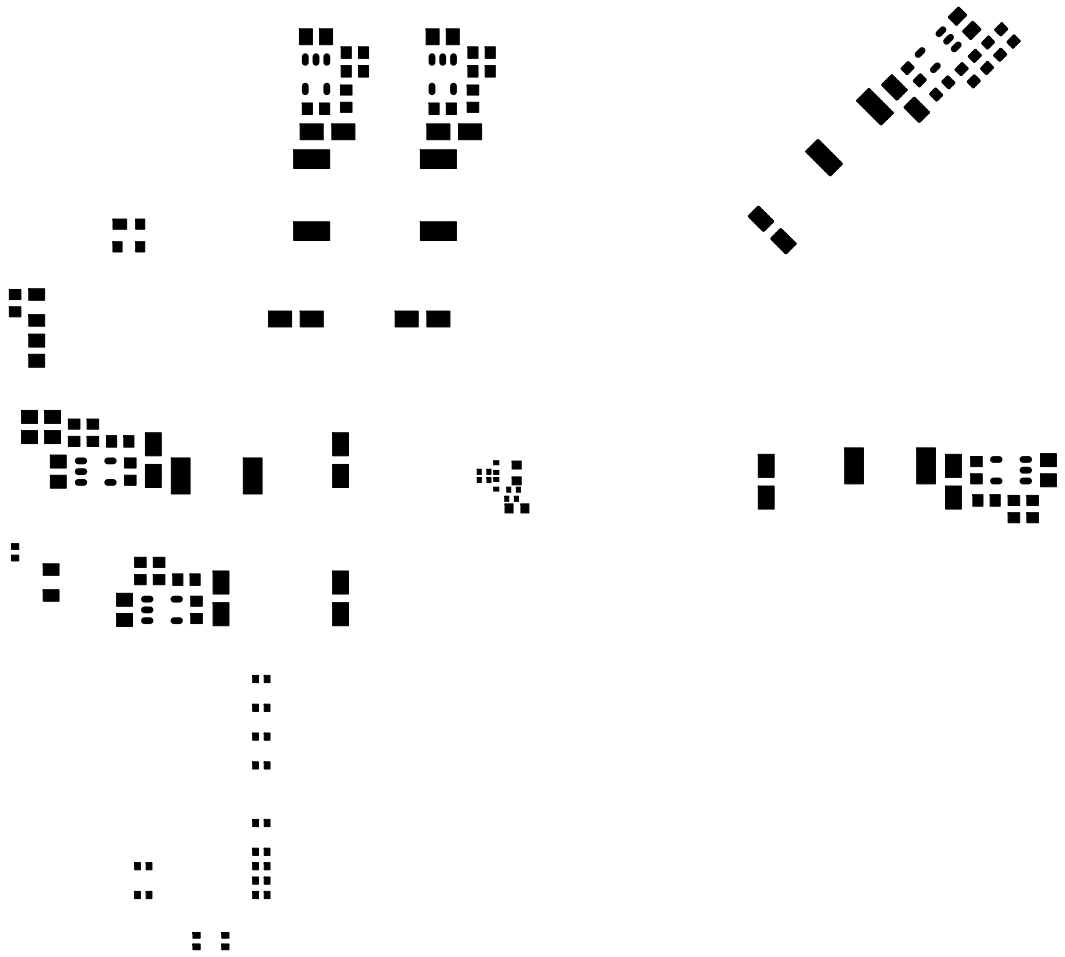


SECONDARY SOLDER MASK

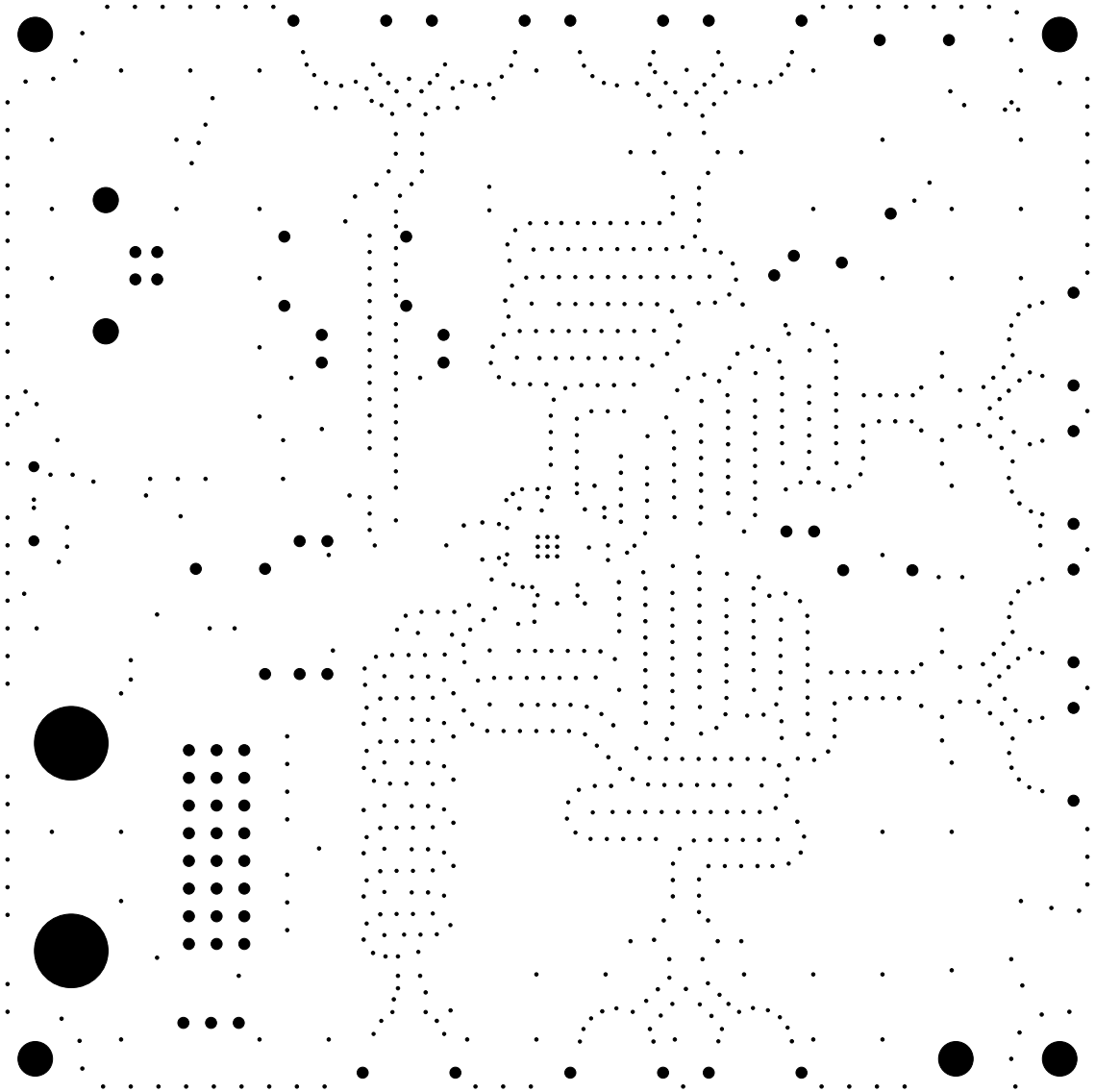
SECONDARY SILKSCREEN

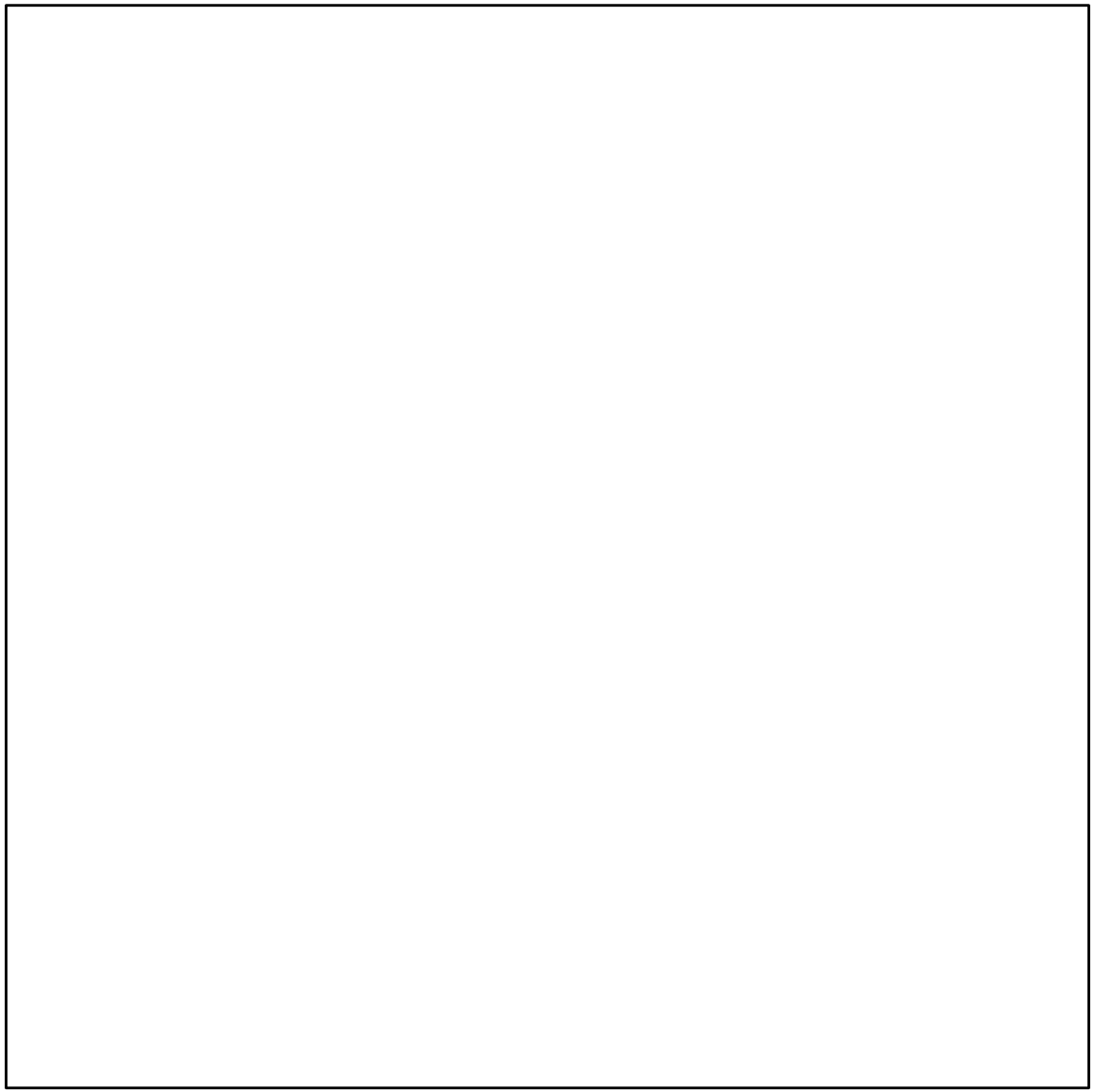


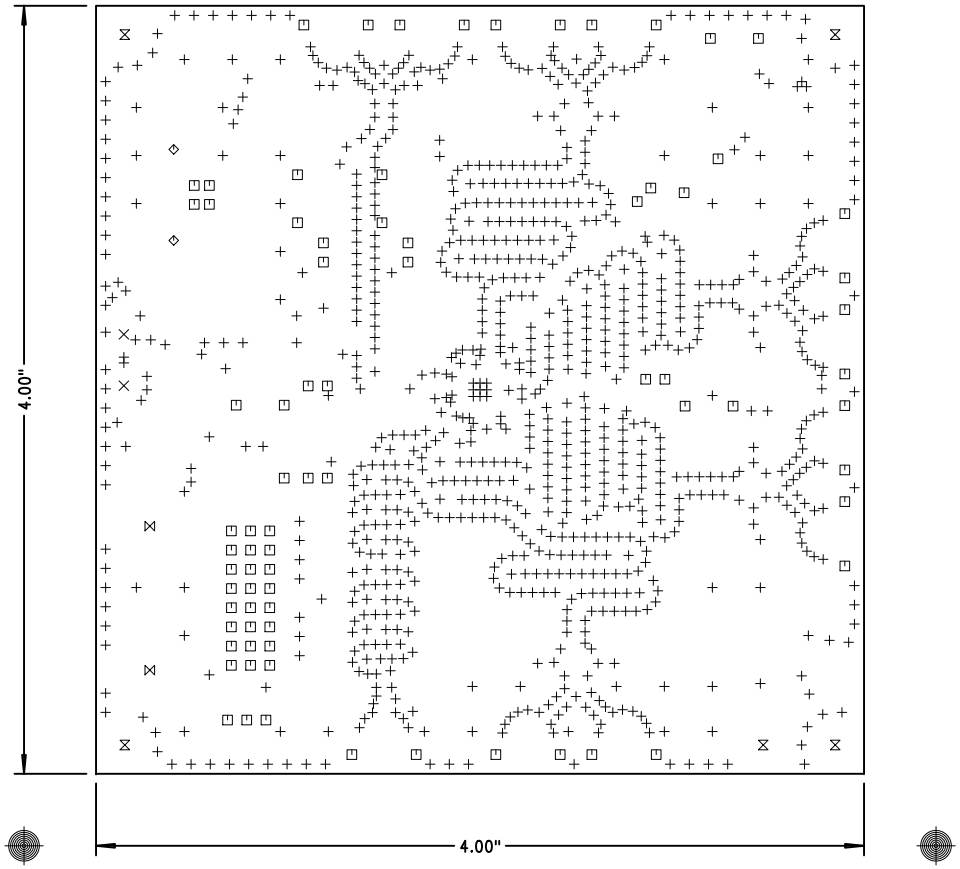
PRIMARY SOLDER PASTE



SECONDARY SOLDER PASTE







PRIMARY DRILL

NOTES : UNLESS OTHERWISE SPECIFIED

1. MANUFACTURE IN ACCORDANCE WITH IPC-6012, TYPE 3, CLASS 2.
2. END PRODUCT FEATURES SHALL NOT VARY MORE THAN 20% FROM ARTWORK ORIGINALS.
3. LAMINATE AND PREPREG SHALL BE AS PER IPC-4101/26,83,98 WITH A DECOMPOSITION TEMPERATURE >= 345°C, COLOR, NATURAL.
4. COPPER WEIGHT SHALL BE 1.0 OZ./SQ. FT. BEFORE PLATING.
5. ALL PLATED THROUGH HOLES SHALL HAVE A MINIMUM OF 0.001" COPPER.
6. DRILL HOLE TOLERANCE AFTER PLATING SHALL BE ±0.003".
7. MINIMUM ANNULAR RING SHALL BE 0.001".
8. MINIMUM ANNULAR RING AT EMERGENT CONDUCTORS SHALL BE 0.003".
9. FINAL PCB THICKNESS SHALL BE 0.062" ±10%.
10. WARP/TWIST SHALL NOT EXCEED 1.0%
11. FINISH SHALL BE LPI, BLUE S.M.O.B.C., BALANCE ENIG.
12. SILKSCREEN WITH NONCONDUCTIVE WHITE EPOXY INK.
13. VENDOR TO PROVIDE PCB MICRO-SECTION OF COUPON AREA & TDR TEST REPORT.
14. REFERENCE ADDITIONAL FAB NOTES IN FILE README.TXT

DO NOT ADJUST SPECIFIED GEOMETRIES WITHOUT NOTIFICATION.

GERBER FILENAME	LAYER	SINGLE ENDED IMPEDANCE		DIFFERENTIAL IMPEDANCE			BASE COPPER WEIGHT (BEFORE PLATING)	THICKNESS (INCH)
		IMPEDANCE (OHMS)	TRACE WIDTH (MM)	IMPEDANCE (OHMS)	TRACE WIDTH (MM)	TRACE GAP (MM)		
52200-QFN32_PSS.PHO	PRIMARY SILKSCREEN							
52200-QFN32_PSM.PHO	PRIMARY SOLDER MASK							
52200-QFN32_PRI.PHO	L01 PRIMARY (Signal)	50	0.15	100	0.15	0.35	0.5 oz	3.74MIL
	370HR							
52200-QFN32_L02.PHO	L02 PLANE (GND)						1.0 oz	14.00MIL
	370HR							
52200-QFN32_L03.PHO	L03 PLANE (GND)						1.0 oz	17.16MIL
	370HR							
52200-QFN32_L04.PHO	L04 PLANE (+5V/ROUTE)						1.0 oz	14.00MIL
	370HR							
52200-QFN32_L05.PHO	L05 PLANE (GND)						1.0 oz	3.74MIL
	370HR							
52200-QFN32_SEC.PHO	L06 SECONDARY (Signal)	50	0.15	100	0.15	0.35	0.5 oz	
52200-QFN32_SSM.PHO	SECONDARY SOLDER MASK							
52200-QFN32_SSS.PHO	SECONDARY SILKSCREEN							

0.062"

SIZE	QTY	SYM	PLT	TOOL	TOL
0.012	968	+	P	1	+0/-0.012
0.036	2	X	N	2	+/-0.003
0.040	78	□	P	3	+/-0.003
0.091	2	◇	P	4	+/-0.003
0.125	5	⧖	N	5	+/-0.003
0.266	2	⋈	P	6	+/-0.003

UNLESS OTHERWISE SPECIFIED

DIMENSIONS ARE IN INCHES AND APPLY AFTER FINISH

INTERPRET DRAWING PER MIL-D-1000

TOLERANCES

HOLE TOLERANCES PER 78027

DECIMALS	ANGLES	SURFACES
.XX +/- .XXX +/-	+/-	MICROINCHES

PART TO BE FREE OF BURRS

BREAK EDGES	BEND RADIUS	BEND RELIEF
MAX	MAX	MAX

DESIGN	RK	11MAY2017
LAYOUT	AA	16MAY2017

DO NOT SCALE DRAWING

COMPANY: SILICON LABS
400 W Cesar Chavez
AUSTIN, TX 78701
(512)416-8500
www.silabs.com

NAME: Si52204-EVB
4-OUTPUT-QFN32

REV : 2.0

SIZE A

PART NUMBER: .

SCALE 1:1

FABRICATION DRAWING

SHEET 1 OF 1